Call for Papers
a Session on

Digital Design and Manufacturing

2016 ASME/ISCIE International Symposium on Flexible Automation (ISFA2016)
InterContinental Hotel & Conference Center
August 1-3, 2016, Cleveland, Ohio, USA

Session Technical Focus

This technical session is focused on the fundamental research and development of computational tools related to product design and manufacturing processes. This includes research activities on all aspects of product development: design, analysis, optimization, process planning, inspection and manufacturing. Relevant work should place a special emphasis on the computational methodologies underlying research in these areas. We cordially invite you to submit a paper to share your knowledge and expertise in all areas related to **Digital Design and Manuf**. Papers from the industrial sector are particularly encouraged. The session welcomes both theoretical and applied papers in areas including, but not limited to:

CAD/CAM/CAPP/CAE techniques	Geometric modeling and optimization
Heterogeneous material modeling and design	Multi-scale shape modeling and design
Functional material modeling and design including structural, electrical, optical, etc.	New digital technology enabled applications including biomedical, robotics, etc.
Simulation-driven product development	Geometric problems in manufacturing
Additive manufacturing / 3D and 4D printing	Design for additive manufacturing

Manufacturing performance modeling and optimization

Paper Submission

The deadline for submission of your contribution to this session is **February 29, 2016**. Both short and long papers will be considered and reviewed. For short papers, please submit a summary of 1,000 words or less (short papers will be limited to 4 pages) and, for long papers, please submit a manuscript of no more than eight pages. All summaries and manuscripts should be submitted through the conference website at **http://engineering.case.edu/conference/ISFA2016/**.

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